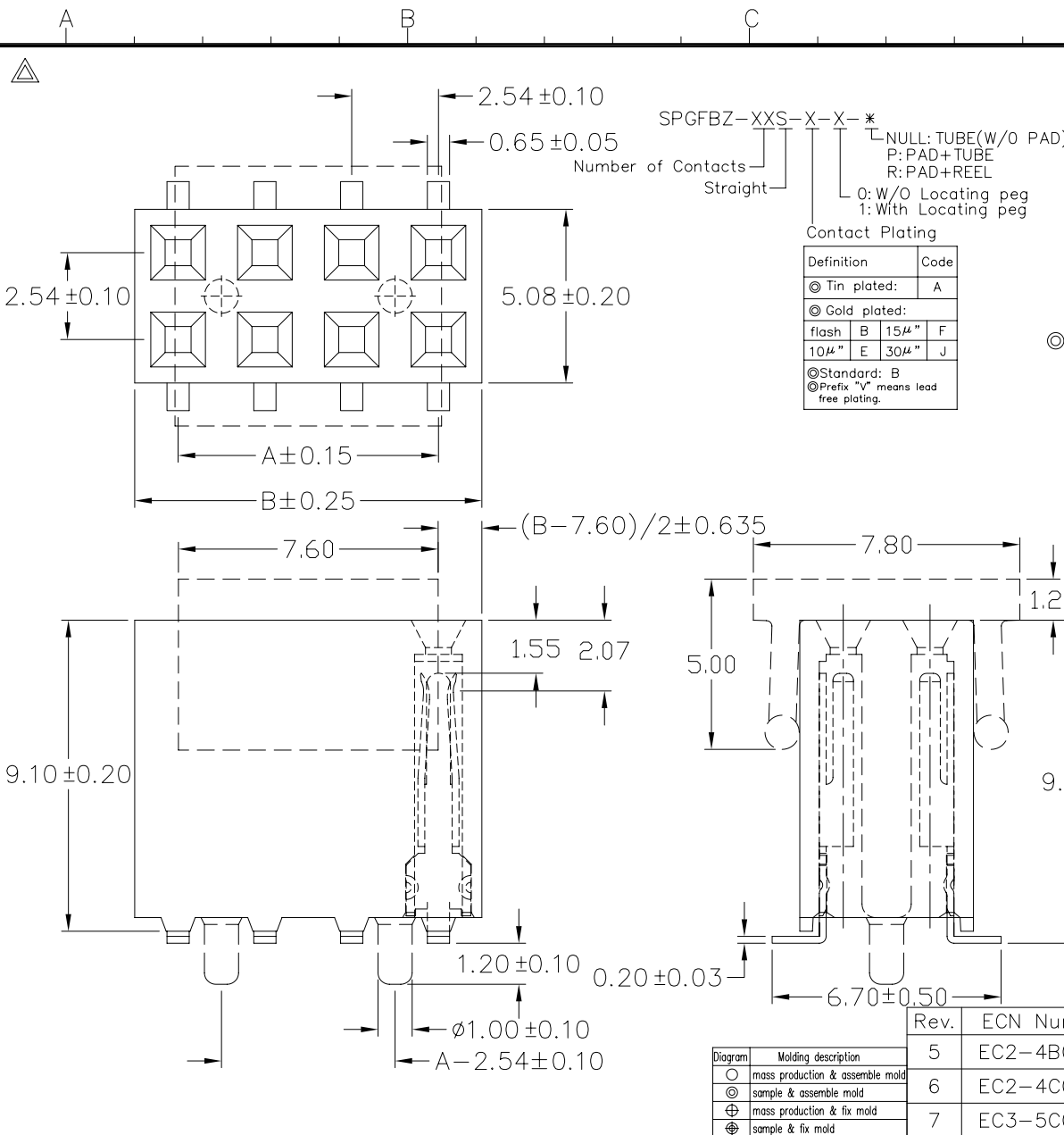


No. of Contacts	DIMENSIONS		W/O PEG WITH PEG	
	A	B	(備註)	
6	5.08	7.62	⊕	
8	7.62	10.16	⊕	⊕
10	10.16	12.70	⊕	⊕
12	12.70	15.24	⊕	⊕
14	15.24	17.78	⊕	⊕
16	17.78	20.32	⊕	⊕
18	20.32	22.86	⊕	⊕
20	22.86	25.40	⊕	⊕
22	25.40	27.94	⊕	⊕
24	27.94	30.48	⊕	⊕
26	30.48	33.02	⊕	⊕
28	33.02	35.56	⊕	⊕
30	35.56	38.10	⊕	⊕
32	38.10	40.64	⊕	⊕
34	40.64	43.18	⊕	⊕
36	43.18	45.72	⊕	⊕
38	45.72	48.26	⊕	⊕
40	48.26	50.80	⊕	⊕
42	50.80	53.34	⊕	⊕
44	53.34	55.88	⊕	⊕
46	55.88	58.42	⊕	⊕
48	58.42	60.96	⊕	⊕
50	60.96	63.50	⊕	⊕
52	63.50	66.04	⊕	⊕
54	66.04	68.58	⊕	⊕
56	68.58	71.12	⊕	⊕
58	71.12	73.66	⊕	⊕
60	73.66	76.20	⊕	⊕
62	76.20	78.74	⊕	⊕
64	78.74	81.28	⊕	⊕
66	81.28	83.82	⊕	⊕
68	83.82	86.36	⊕	⊕
70	86.36	88.90	⊕	⊕
72	88.90	91.44	⊕	⊕
74	91.44	93.98	⊕	⊕
76	93.98	96.52	⊕	⊕
78	96.52	99.06	⊕	⊕
80	99.06	101.60	⊕	⊕



SPECIFICATIONS

Current Rating: 3 Amps
 Insulator resistance: 5000 Megohms Min.
 Contact resistance: 20 m ohm Max.
 Dielectric withstanding: AC 250 V
 Contact Material: Phosphor bronze
 Insulator Material: High Temperature Thermoplastic, UL 94V-0
 Color: Black

Finish: Tin, Gold or Duplex plated

⊙ Note:
 Duplex plating: gold plated on contact area, Tin on solder area

Recommended PCB Layout
 (PCB TOLERANCE ±0.05)

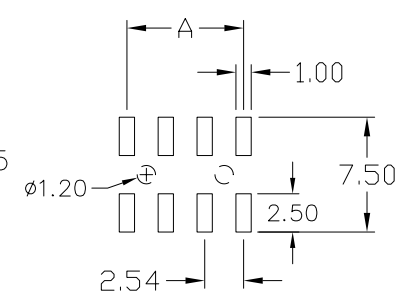


Diagram	Molding description	Rev.	ECN Number	Description	Drawn	Date
○	mass production & assemble mold	5	EC2-4B0419	新增環保電鍍	陳美竹	11/23 04'
⊙	sample & assemble mold	6	EC2-4C0737	修改備註, 新增導柱選項, 修改料號 SPGFZ-XXS-X-0-* -> SPGFZ-XXS-X-X-*	洪銀雯	12/30 04'
⊕	mass production & fix mold	7	EC3-5C0015	修正規格說明	胡祥龍 / 詹益東	12/13 05'
⊙	sample & fix mold					

DATE 12-07-02'	DWG. NO. 3-15	TITLE 2.54X2.54mm SMD SOCKET (成品規格圖)	REV. 7
DATE 12/13 05'	F: \DWG\CDWG\PGFB\PGFBZMOA.DWG		SHEET 1/1
DATE 12/13 05'	PARTS NO. SPGFZ-XXS-X-X-*		



GENERAL TOLERANCE	SCALE 1=1	ORIGINAL DRAWN 邱若婷	DATE 12-07-02'
XX. ± 0.40	UNIT MM	CHECK 林錫錦	DATE 12/13 05'
XXX. ±	SIZE A4/5	APPROVE 林錫錦	DATE 12/13 05'
X. ± 0.25			
.X ± 0.15			
.XX ± 0.10			